LiPOLY®
SHIU LI TECHNOLOGY CO.,LTD

DTT65-s

Lightweight Thermal Conductive Gel Pad

LiPOLY DTT65-s is a soft thermally conductive gel pad specifically designed for network ing communication applications.DTT65-s is designed to focus on D_k and D_f to reduce interference in RF modules. DTT65-s has a thermal conductivity of 5.0 W/m*K. This product can be supplied as stan dard sheets, custom die-cuts or custom molded parts making it suitable for a wide range of applications.

FEATURES

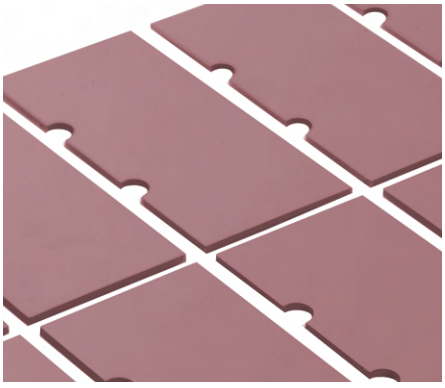
/ Lightweight, Low Density
Thermal conductivity: 5.0 W/m*K
/ Hardness: Shore OO/50
/ Low dielectric constant
/ For high frequency applications
/ Available in a range of thicknesses

TYPICAL APPLICATION

/ Communications satellite
/ Satellite positioning devices
/ IoT devices
/ Telecommunication hardware
/ 5G base station & infrastructure
/ EV electric vehicle

SPECIFICATIONS

/ Sheet form
/ Die-cut parts



TYPICAL PROPERTIES

PROPERTY	DTT65-s	TEST METHOD	UNIT
Color	Red	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	2.1	ASTM D792	g/cm³
Hardness	55	ASTM D2240	Shore OO
Water absorption	0.005	ASTM D570	%
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	8	ASTM D5470 modify	%
Deflection @20 psi	11	ASTM D5470 modify	%
Deflection @30 psi	16	ASTM D5470 modify	%
Deflection @40 psi	21	ASTM D5470 modify	%
Deflection @50 psi	26	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	10	ASTM D149	KV/mm
Surface resistivity	$>10^{12}$	ASTM D257	Ohm
Volume resistivity	$>10^{13}$	ASTM D257	Ohm-m
Dielectric constant@2GHz D_k	4.131	ASTM D150	-
Dielectric constant@6GHz D_k	4.058	ASTM D150	-
Dielectric constant@10GHz D_k	4.013	ASTM D150	-
Dissipation factor@2GHz D_f	0.00509	ASTM D150	-
Dissipation factor@6GHz D_f	0.00658	ASTM D150	-
Dissipation factor@10GHz D_f	0.00780	ASTM D150	-
THERMAL			
Thermal conductivity	5.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.350	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.342	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.323	ASTM D5470	°C-in²/ W
Thermal impedance@40 psi	0.302	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.281	ASTM D5470	°C-in²/ W

Thermal Resistance vs. Pressure vs. Deflection